

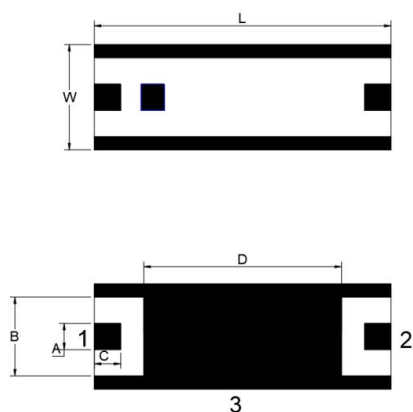
Features

- Multilayer monolithic construction yields high reliability
- Low insertion loss and small size SMD chip design
- Can simplify your complex tuning and circuit design
- LTCC process

Specifications

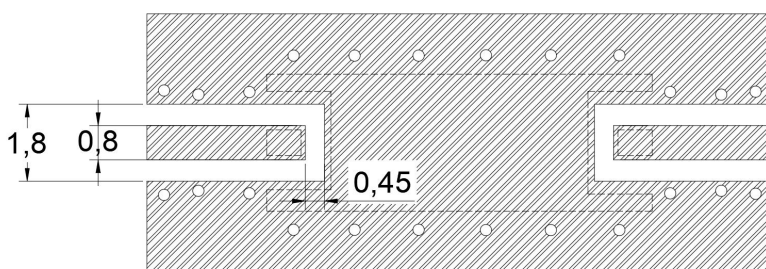
NO.	Parameter		SPEC
1	Frequency (MHz)		5500~6000
2	Insertion Loss (dB) @25℃		≤2.2
3	Ripple (dB)		≤1.0
4	VSWR(In BW)		≤1.8
5	Attenuation(dBc)	DC~5000MHz	≥37
		6450~9000MHz	≥37
7	In/Output Impedance (Ω)		50
8	Power		5W
Operating & Storage Condition (Component) Operation Temperature Range: -40℃ ~ +85℃ Storage Temperature Range: -40℃~ +85℃			
Storage Condition before Soldering (Included packaging material) Storage Temperature Range: +5 ~ +40 ℃ Humidity: 30 to 70% relative humidity			

Construction



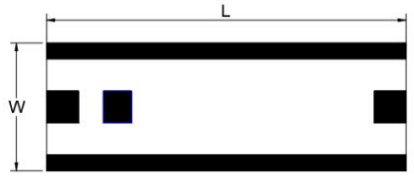
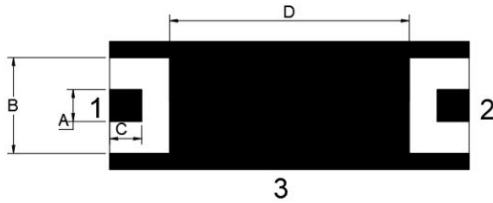
PIN	Connection
1	Input Port
2	Output Port
3	GND

Mounting Considerations

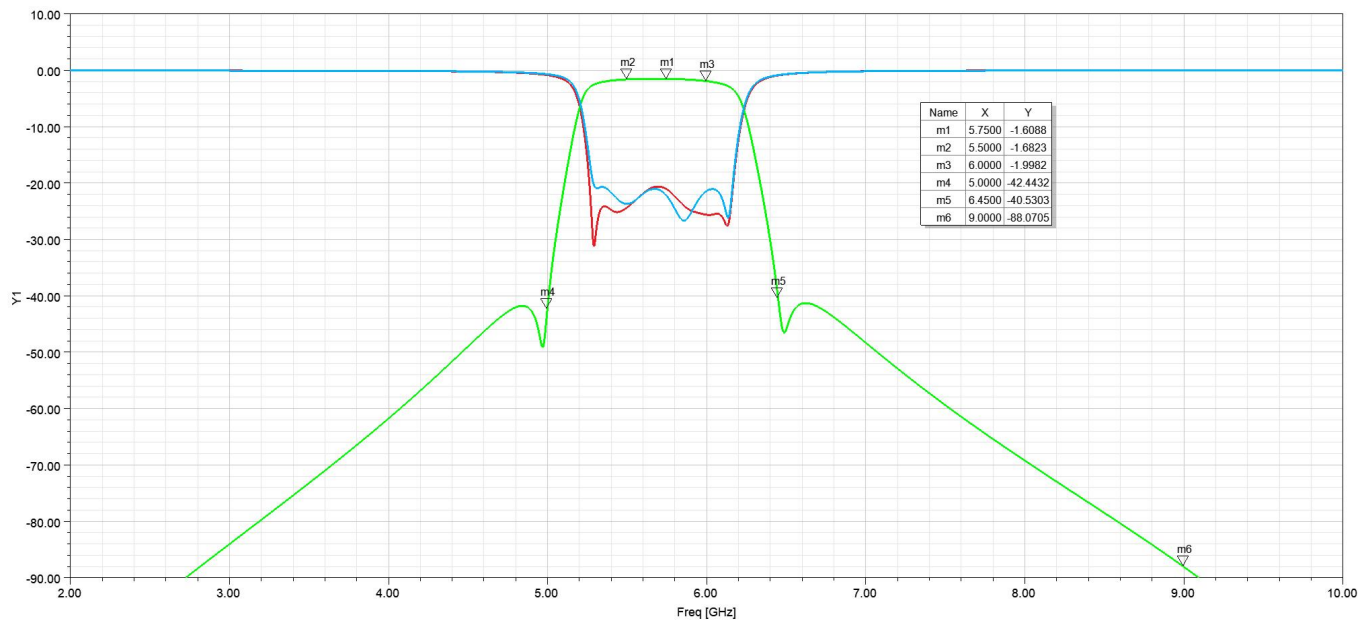


Unit: mm

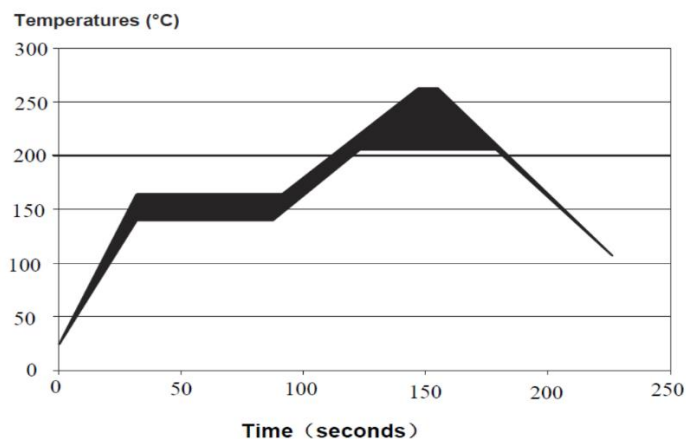
Dimensions

Figure	Symbol	Dimension (mm)
	L	9.00 ± 0.20
	W	3.20 ± 0.20
	T	1.50 ± 0.20
	A	0.60 ± 0.15
	B	2.40 ± 0.15
	C	0.80 ± 0.15
	D	6.00 ± 0.15

Typical Electrical Characteristics (T=25°C)



Solder Reflow Standard Conditioning



Storage Conditions

Temperature : +5 to +30 °C

Humidity : 20 to 70% RH

Term of storage : Within 12 months (After the delivery) *

Baking : Unnecessary

* After peeling off cover tape, do not keep exposing the products to the open air. For the products stored longer than 12 months, confirm their terminals and solderability before use.